

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein an amount of the slip additive is in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.
2. (Original) The heat-resistant film according to claim 1, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.
3. (Currently Amended) ~~The heat-resistant film according to claim 1,~~ A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is polymethylmethacrylate.
4. (Canceled)

5. (Currently Amended) ~~The heat-resistant film according to claim 1,~~ A heat-resistant film comprising a film substrate and a heat-resistant slip layer disposed on one surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.
6. (Canceled)
7. (Currently Amended) The heat-resistant film according to claim 23, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.
8. (Currently Amended) The heat-resistant film according to claim 23, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.
9. (Currently Amended) The heat-resistant film according to claim 35, wherein the

heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

10-12. (Canceled)

13. (Currently Amended) The heat-resistant film according to claim 6~~7~~, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.

14-16. (Canceled)

17. (Currently Amended) A thermal transfer recording medium including a film substrate and a thermal transfer ink layer disposed on one surface of the film substrate and a heat-resistant slip layer disposed on the other surface of the film substrate, the heat-resistant slip layer comprising a binder and a slip additive, wherein the slip additive is a higher fatty acid metal salt composition comprising a free higher fatty acid in an amount of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein an amount of the slip additive is in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.

18. (Original) The thermal transfer recording medium according to claim 17, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is

aluminum stearate.

19. (Currently Amended) ~~The thermal transfer recording medium according to claim~~  
17, A thermal transfer recording medium including a film substrate and a thermal  
transfer ink layer disposed on one surface of the film substrate and a heat-resistant  
slip layer disposed on the other surface of the film substrate, the heat-resistant slip  
layer comprising a binder and a slip additive, wherein the slip additive is a higher  
fatty acid metal salt composition comprising a free higher fatty acid in an amount  
of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein the binder is  
polymethylmethacrylate.
20. (Canceled)
21. (Currently Amended) ~~The thermal transfer recording medium according to claim~~  
17, A thermal transfer recording medium including a film substrate and a thermal  
transfer ink layer disposed on one surface of the film substrate and a heat-resistant  
slip layer disposed on the other surface of the film substrate, the heat-resistant slip  
layer comprising a binder and a slip additive, wherein the slip additive is a higher  
fatty acid metal salt composition comprising a free higher fatty acid in an amount  
of 3 to 30wt% and a metal salt of a higher fatty acid, and wherein a high glass  
transition temperature resin layer having a higher glass transition temperature than  
the binder of the heat-resistant slip layer is interposed between the film substrate  
and the heat-resistant slip layer.

22. (New) The heat-resistant film according to claim 3, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.
23. (New) The heat-resistant film according to claim 5, wherein the free higher fatty acid is stearic acid and the metal salt of higher fatty acid is aluminum stearate.
24. (New) The heat-resistant film according to claim 22, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.
25. (New) The heat-resistant film according to claim 22, wherein a high glass transition temperature resin layer having a higher glass transition temperature than the binder of the heat-resistant slip layer is interposed between the film substrate and the heat-resistant slip layer.
26. (New) The heat-resistant film according to claim 23, wherein the heat-resistant slip layer comprises the slip additive in an amount of 3 to 9 parts by weight with respect to 100 parts by weight of the binder.